


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	POWER AND DISCRETES/26/16369	
1.3 Title of PCN	STGD10HF60KD (DPAK): Capacity Extension at ATX Melaka (Malaysia).	
1.4 Product Category	Pls refer to the impacted IGBT product list.	
1.5 Issue date	2026-05-19	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Angelo RAO
2.1.2 Marketing Manager	Paolo PETRALI
2.1.3 Quality Manager	Massimiliano CUOZZO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China) and ATX Melaka (Malaysia) as Assy Manufacturing Plant.

4. Description of change

	Old	New
4.1 Description	ST Shenzhen (China) as Assy Manufacturing Plant	ATX Melaka (Malaysia) as additional Assy Manufacturing Plant
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Impact on Processability.	

5. Reason / motivation for change

5.1 Motivation	Increasing back-end capacity out of China.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	by the first two digits of the traceability code ("9M"), by internal code (Finished Good ending with \$Ix) and Q.A. number.
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7. Timing / schedule

7.1 Date of qualification results	2026-07-10
7.2 Intended start of delivery	2026-11-27
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

16369 Public product.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STGD10HF60KD	

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